Dual N-Channel Driver with Diagnostic Output 60 V, 3 A, 110 m Ω

NIMD6001N/AN is a dual 3 Amp low-side switch with an integrated common disable input and drain diagnostic output. Pulling the Disable pin low will override any applied gate voltages and turn off both FET switches. Should either Drain-Source voltage exceed approximately 50 V, a logic 1 (> 3 V) will be asserted on the Diagnostic/Feedback pin. Internal isolation diodes permit the Disable and Diagnostic/ Feedback pins of multiple devices to be interconnected in a "wired-OR" configuration without additional components.

Features

- R_{DSON} 110 m Ω Maximum at V_{GS} = 10 V
- Avalanche Energy Specified
- Gate Drive Disable Input
- Drain-Source Voltage Diagnostic Feedback Output
- Electrically Isolated Drains for Low Crosstalk
- Internal Resistors Limit Peak Transient gate Current
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Automotive Injector Driver
- Solenoid / Relay Driver

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage (DC, sustained)	V_{DSS}	60	Vdc
Gate-to-Source Voltage	V _{GS}	±20	Vdc
Continuous Drain Current V_{GS} = 10 V, $R_{\theta JA}$ = 55°C/W V_{GS} = 5.0 V, $R_{\theta JA}$ = 55°C/W	Ι _D	3.3 3.0	Α
Single Pulse Drain Current Pulse duration = 80 μs	Ι _D	10	Α
Single Pulse Drain-to-Source Avalanche Energy V _{DD} = 60 V; V _{GS} = 10 V; I _{PK} = 2.6 A; L = 76 mH; Start Tj = 25°C	E _{AS}	258	mJ
Operating Junction Temperature	T _J	-55 - 150	°C
Storage Temperature	T _{STG}	-55 - 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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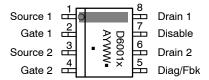
3.0 AMPERES 60 VOLTS

 $R_{DS(on)} = 110 \text{ m}\Omega$



SOIC-8 CASE 751

MARKING DIAGRAM



(Top View)

D6001x = Specific Device Code

x = N or A

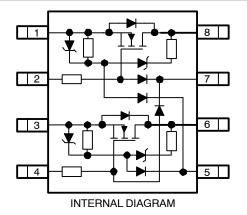
A = Assembly Location

′ = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)



ORDERING INFORMATION

Device	Package	Shipping
NIMD6001NR2G	SOIC-8 (Pb-Free)	2500/Tape & Reel
NIMD6001ANR2G	SOIC-8 (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

PIN DESCRIPTIONS

Pin #	Symbol	Description
1	S1	FET 1 Source and Body
2	G1	FET 1 Gate
3	S2	FET 2 Source and Body
4	G2	FET 2 Gate
5	Diag/Fbk	Diagnostic Feedback – This pin will be logic high when either FET Drain-Source voltage exceeds the Drain Diagnostic threshold.
6	D2	FET 2 Drain
7	Disable	Gate Disable – Pull this pin low to disable both FETs. A logic low will override voltage applied to G1 or G2.
8	D1	FET 1 Drain

THERMAL RESISTANCE

Parameter	Symbol	Value	Units
Junction-to-Ambient - min. pad footprint (Notes 1 and 2)	$R_{ heta JA}$	96	°C/W
Junction-to-Ambient – 1" Cu pad (Notes 1 and 3)	$R_{ heta JA}$	75	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
OFF CHARACTERISTICS					•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V; I _D = 5 mA	60	67		V
Zero Gate Voltage Drain Current (Note 1)	I _{DSS}	V _{GS} = 0 V; V _{DS} = 15 V V _{GS} = 0 V; V _{DS} = 15 V; T _A = 150°C		10 80	20 250	μΑ
Gate Input Current	I _{GSS}	V _{GS} = ±20 V; V _{DS} = 0 V	-100	±25	+100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	$V_{DS} = V_{GS}; I_D = 250 \mu A$	1.0	1.7	3.0	
Static Drain-to-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10 V; I _D = 3.3 A		60	110	mΩ
Static Drain-to-Source On-Resistance	R _{DS(ON)}	V _{GS} = 5 V; I _D = 3.0 A		72	130	mΩ
DYNAMIC CHARACTERISTICS (Note 1)						
Input Capacitance	C _{ISS}			150	175	pF
Output Capacitance	C _{OSS}	$V_{GS} = 0 \text{ V}; V_{DS} = 15 \text{ V};$ f = 75 kHz		150	170	
Reverse Transfer Capacitance	C _{RSS}	1 - 70 1112		25	30	-
Gate Resistance	R_{G}			8	15	kΩ
Total Gate Charge	Q _{g(TOT)}			8.3	9.0	nC
Gate-to-Source Gate Charge	Q _{gs}	$V_{GS} = 0 \text{ V to 5 V; } V_{DD} = 30 \text{ V;}$ $I_{D} = 3.3 \text{ A; } I_{G} = 1.0 \text{ mA,}$		1.1	1.6	
Gate-to-Drain Miller Charge	Q_{gd}	- 1 _D = 5.57, 1 <u>G</u> = 1.0 m/s,		4.2	5	

- 1. These values are established by statistical characterization and may not be tested.
- Surface-mounted on FR4 board using the minimum recommended pad size (Cu area = 40 sq. mm; 1 oz.)
 Surface-mounted on FR4 board using 1 sq. inch heat spreader (Cu area = 625 sq. mm, 2 oz.)
 Refer to Figure 1 for definition of switching characteristics symbols.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
SWITCHING CHARACTERISTICS (Note	es 1 and 4)					
Turn-On Time	T(on)			6.0	8.0	μs
Turn-On Delay	Td(on)	$V_{GS} = 10 \text{ V}; V_{DD} = 30 \text{ V};$		1.7		1
Rise Time	Tr	I_D = 3.3 A, Ext. R_{GS} = 47 Ω		3.9		1
Turn-Off Time	T(off)			24	28	1
Turn-Off Delay	Td(off)			15		1
Fall Time	Tf			9.0		1
BODY DIODE						
Source-Drain Forward On Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_{SD} = 3.3 \text{ A}$		0.85	1.25	V
DIAGNOSTIC FEEDBACK (Note 1)						
Feedback voltage	V _{FBK}	$V_{DS} = 35 \text{ V},$ $R_{FBK-SOURCE} = 51 \text{ k}\Omega$			1.7	V
Feedback Logical High voltage	V _{FBK(HI)}	$V_{DS} = 60 \text{ V},$ $R_{FBK-SOURCE} = 51 \text{ k}\Omega$	3.0		5.5	V
V _{DS} threshold voltage for logical High	V _{DSFBK(HI)}	Ramp V_{DS} positive until $V_{FBK} = 3.5 \text{ V}$	45		65	V
V _{DS} threshold voltage for logical Low	V _{DSFBK(LOW)}	Ramp V_{DS} negative until $V_{FBK} = 0.8 \text{ V}$	25		45	V
DISABLE (Note 1)						
Gate Drive Disable Input Voltage, Gate Enable	V _{DIS(HI)}	$V_{DIS} \ge 3.0 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 3.0 \text{ A}$	3			V
Gate Drive Disable Input Voltage, Gate Disable	V _{DIS(LOW)}	$V_{DIS} \le 0.4 \text{ V}, V_{GS} = V_{DS} = 10 \text{ V}, \\ I_D \le 250 \mu\text{A}; \text{ Tj} = 150 ^{\circ}\text{C} \text{ (Note 1)}$			0.4	٧

- These values are established by statistical characterization and may not be tested.
- 2. Surface-mounted on FR4 board using the minimum recommended pad size (Cu area = 40 sq. mm; 1 oz.)
- Surface-mounted on FR4 board using 1 sq. inch heat spreader (Cu area = 625 sq. mm, 2 oz.)
 Refer to Figure 1 for definition of switching characteristics symbols.

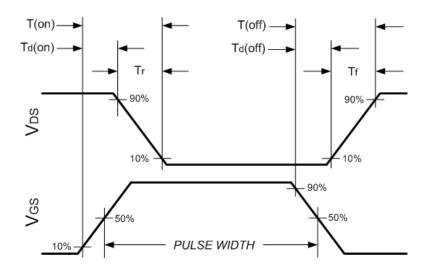
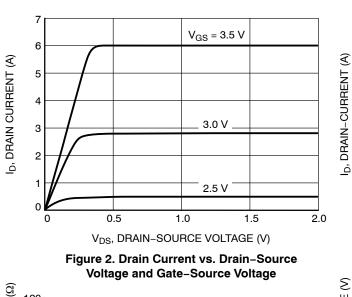


Figure 1. Switching Characteristics Waveforms and Symbols

TYPICAL ELECTRICAL CHARACTERISTICS



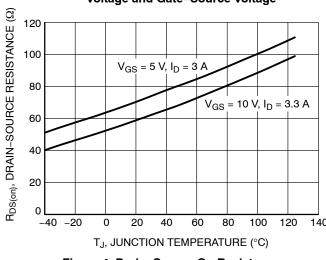


Figure 4. Drain-Source On Resistance vs.
Junction Temperature

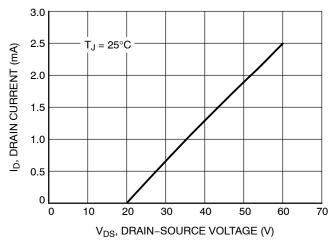


Figure 6. Off-State Drain Current vs.

Drain-Source Voltage (includes feedback network current)

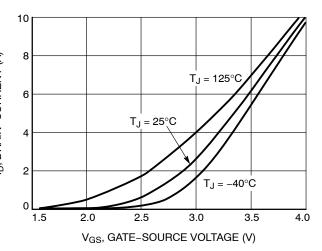


Figure 3. Transfer Function (pulsed). Pulse duration = 80 μ s, duty cycle < 0.5%; V_{DS} = 2 V

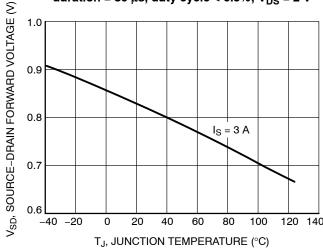


Figure 5. Body Diode Forward Voltage vs.
Junction Temperature

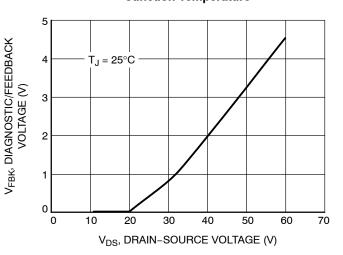


Figure 7. Diagnostic Feedback Voltage vs.
Drain-Source Voltage

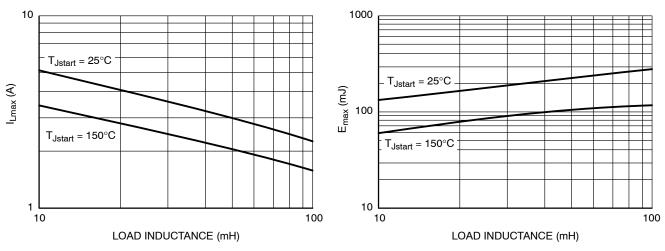


Figure 8. Single Pulse Maximum Switch-off Current vs. Load Inductance

Figure 9. Single Pulse Maximum Switching Energy vs. Load Inductance

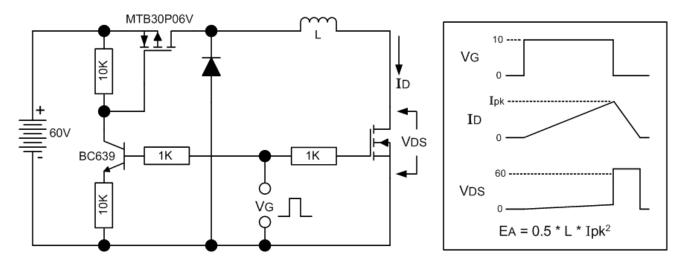


Figure 10. Single Pulse Peak Drain Current and Avalanche Energy Test Circuit

TYPICAL THERMAL RESPONSE CHARACTERISTICS

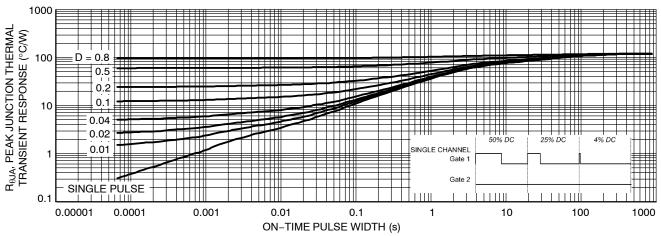


Figure 11. Single Channel Active; Mounted on Minimum-Pad Board

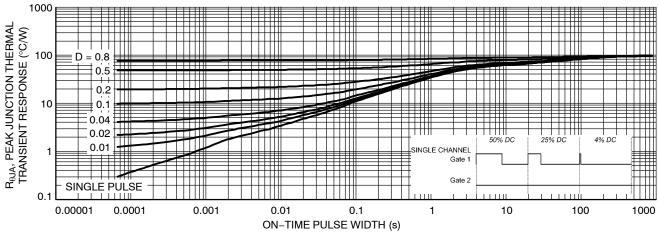


Figure 12. Single Channel Active; Mounted on 1 Sq. Inch Copper Spreader

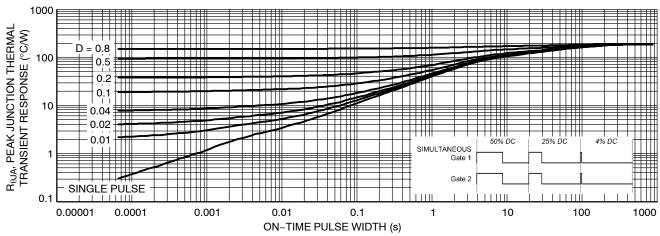


Figure 13. Both Channels Active; Mounted on Minimum-Pad Board

TYPICAL THERMAL RESPONSE CHARACTERISTICS

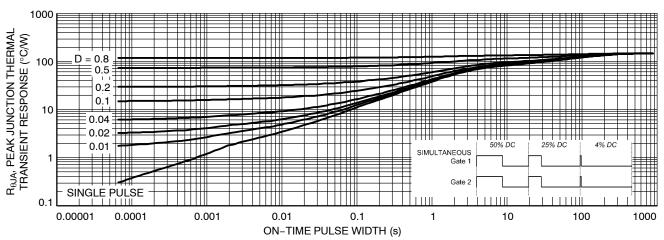


Figure 14. Both Channels Active; Mounted on 1 Sq. Inch Copper Spreader

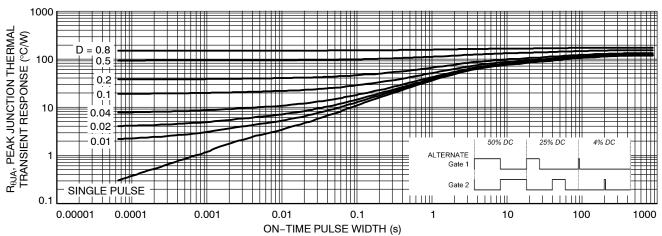


Figure 15. Channels Alternatively Active; Mounted on Minimum-Pad Board

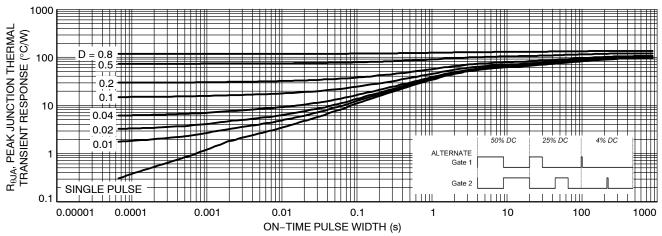


Figure 16. Channels Alternatively Active; Mounted on 1 Sq. Inch Copper Spreader

TYPICAL APPLICATION CIRCUIT

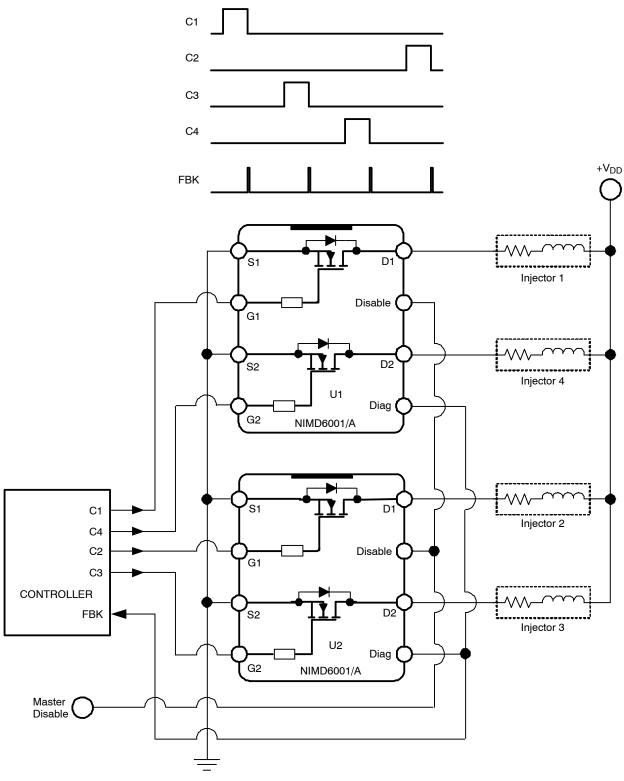
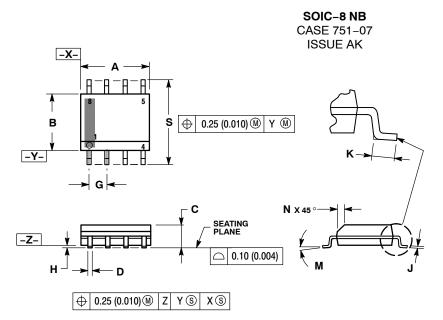


Figure 17. 4 Cylinder Engine Fuel Injection

- 4-Cycle engine; 1 injector pulse during intake stroke
- To optimize transient thermal resistance of the NIMD6001/A devices, the injector drive pulses are alternated between U1 and U2.
- Cylinder firing order is 1-3-4-2
- The coincident FBK pulse will be missing if any injector is open or shorted.

PACKAGE DIMENSIONS

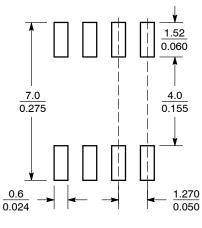


NOTES:

- DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND DO NOT INCLUDE
 MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT
- MAXIMUM MATERIAL CONDITION. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.05	0 BSC	
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 ° 8		
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

SOLDERING FOOTPRINT*



mm SCALE 6:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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